

US-PAT-NO: 5914157

DOCUMENT-IDENTIFIER: US 5914157 A

See image for Certificate of Correction

TITLE: Solventless hot melt process for the
preparation of pressure sensitive adhesives

----- KWIC -----

Detailed Description Text - DETX (90):

The equipment and conditions employed in Example 2 were repeated, with the following exceptions. A non-thermosettable phenolic tackifying resin, SP-1068 (available from Schenectady Chemical Co.), was added to conveying zone C6 along with the Vanax MBM at a rate of 0.09 lbs/min (41 gm/min) using the same loss-in-weight feeder used to deliver the Vanax MBM. An additional 0.27 lbs/min (120 gm/min) of Piccotac.TM. B was also added with this same loss-in-weight feeder to prevent "bridging", or "cavitation", in the hopper above the feeder. The pressures measured in the flexible hose leading to the die measured 2000 psig (13.8 mPa), an acceptable level given the pressure rating of the hose. The extrudate was now easy to coat evenly and smoothly onto a creped paper backing. The cured coating was found to have the following properties:

Detailed Description Text - DETX (102):

SP-1068--a pure phenolic, non-thermosettable tackifying resin from Schenectady Chemicals, Inc.

Other Reference Publication - OREF (4):

Schenectady Chemicals Inc., Material Data Sheets for
SP-1068, SP-1077,
SP-553, SP-560, SP-6701, and CRJ-418 Resins. (No data
avail.).